© Cor	erial Composition byright 2005. IPC, Bar ational and Pan-Ameri	nockburn, Illinois. A	Il rights reserved untions.	Inder both leve	is documer el parts, th	nt is a declara ne declaration	tion of the su encompasses	ibstances v s all lower	vithin the manufac level materials for	turer listed i which the n	tem. No nanufac	ote: if the it cturer has e	tem is an ass ngineering 1	sembly with lower esponsibility.
					Declaration Class *   istribute Class 6 - RoHS Yes/No, Homogeneous Mat				erials and M	rials and Mfg Information				
Supplier Information														
Company name*	Company un	Company unique ID			Unique ID Authority					Response Date*				
onsemi										2025-07	2025-07-06			
Contact Name	Title - Conta	Title - Contact			Phone - Contact*				Email -	Email - Contact*				
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com				
Authorized Representative*	Title - Repre	Title - Representative			Phone - Representative*				Email -	Email - Representative*				
Product-Env-Stewards		Product Envi	Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com			
Requester Item N	Requester Item Number Mfr Iter		Number Mfr Item Name			Effective Dat	e Version	N	Manufacturing Site		Weight	.* U	JOM	Unit Type
	NCP718BSN330T1G 3		300 mA Low Iq, Wide Input Voltage LDO - TSOT23-5; 3V3 HZ		LDO -	2025-07-06		Т	ТНВ		12.52	n	ng	Each
Manufacturing Procee	ss Information													
Terminal Plating /	inal Plating / Grid Array Material Terminal Ba		Alloy	J-STD-020 MSL Rating		Peak Process Body Temperatu		emperature	re Max Time at Peak Temper		perature Number of Reflow Cycles		les	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		no CU Alloy	CU Alloy 1			260	С		30 seco		seconds 3			
Comments														
evel 1 - maximum time at pe	eak temperature dur	ing soldering is 10-3	0 seconds											
or more information regard	ding material compo	sition please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	to HS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl hthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.3	mg	Supplier	Silicon (Si)	7440-21-3		0.3	mg
Die Attach Epoxy	0.1	mg	Supplier	Poly(oxypropylene)diamine	9046-10-0		0.003	mg
			Supplier	Silver (Ag)	7440-22-4		0.085	mg
			Supplier	Proprietary	Proprietary Data		0.005	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.007	mg
Lead Frame	6.43	mg	Supplier	Zinc (Zn)	7440-66-6		0.0077	mg
			Supplier	Iron (Fe)	7439-89-6		0.1511	mg
			Supplier	Copper (Cu)	7440-50-8		6.2692	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0019	mg
Mold Compound-Black	5.6	mg		Epoxy resin	proprietary data		0.28	mg
			Supplier	Phenolic Resin	Proprietary Data		0.112	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.14	mg
			Supplier	Carbon Black (C)	1333-86-4		0.028	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.04	mg
Plating	0.07	mg	Supplier	Palladium (Pd)	7440-05-3		0.0017	mg
			В	Nickel (Ni)	7440-02-0		0.0616	mg
			Supplier	Gold (Au)	7440-57-5		0.0067	mg
Wire Bond - Cu	0.02	mg	Supplier	Palladium (Pd)	7440-05-3		0.0004	mg
			Supplier	Gold (Au)	7440-57-5		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0196	mg